

IN THE CLAIMS

1 (Currently Amended). A method comprising:

microfabricating a vacuum sensor;
enclosing said vacuum sensor with an integrated circuit inside an enclosure, said
sensor including a serpentine wire; and
suspending supporting said sensor in a raised portion over a substrate on an
upwardly extending contact.

2 (Original). The method of claim 1 including integrating said vacuum sensor and said
integrated circuit in the same substrate.

3 (Original). The method of claim 1 including integrating said vacuum sensor and said
integrated circuit on separate dice and enclosing said separate dice in the same enclosure.

Claim 4 (Canceled).

5 (Currently Amended). The method of claim 1 [[4]] including microfabricating the
sensor as a suspended, serpentine wire.

6 (Currently Amended). The method of claim 1 [[4]] including forming a contact on a
surface, said contact coupled to said wire.

7 (Original). The method of claim 6 including making said contact U-shaped.

8 (Original). The method of claim 1 including providing an enclosure that covers said
vacuum sensor and said integrated circuit and provides a hermetically sealed chamber.

9 (Original). The method of claim 8 including providing an electrical connection under
said enclosure to the exterior of said chamber.

10 (Previously Presented). An integrated circuit device comprising:
a microfabricated vacuum sensor including a serpentine wire, and a contact coupled
to said wire, said contact including a vertical portion extending upwardly to said wire;
an integrated circuit;
an enclosure; and
a substrate, said enclosure mounted on said substrate and enclosing both said
vacuum sensor and said circuit within said enclosure.

11 (Original). The device of claim 10 wherein said vacuum sensor and said integrated
circuit are monolithically integrated in the same die.

12 (Original). The device of claim 10 wherein said vacuum sensor and integrated circuit
are on separate dice.

Claim 13 (Canceled).

14 (Previously Presented). The device of claim 10 wherein said wire is suspended.

Claim 15 (Canceled).

16 (Previously Presented). The device of claim 10 wherein said contact is U-shaped.

Claim 17 (Canceled).

18 (Original). The device of claim 10 wherein said enclosure is hermetically sealed.

19 (Original). The device of claim 18 including an electrical connection extending under
said enclosure to the exterior of said enclosure.

20 (Previously Presented). An integrated circuit device comprising:

a substrate;

a vacuum sensor integrated in said substrate including a serpentine wire, and a contact coupled to said wire, said contact including a vertical portion extending upwardly to said wire;

an integrated circuit integrated in said substrate; and

an enclosure, said enclosure mounted on said substrate and enclosing both said vacuum sensor and said integrated circuit within said enclosure.

Claim 21 (Canceled).

22 (Previously Presented). The device of claim 20 wherein said wire is suspended.

Claim 23 (Canceled).

24 (Previously Presented). The device of claim 20 wherein said contact is U-shaped.

Claim 25 (Canceled).

26 (Original). The device of claim 20 wherein said enclosure is hermetically sealed.

27 (Original). The device of claim 26 including an electrical connection extending under said enclosure to the exterior of said enclosure.